

Notice of References Cited

Application/Control No.

09/915,145

Applicant(s)/Patent Under
Reexamination
NOGAMI ET AL.

Examiner

Thomas J. Mage

Art Unit

2811

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-5,695,810	12-1997	Valery M. Dubin et al.	427/96
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.